

N-Ch MOSFET

General Description

The WSF60N06 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF60N06 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summery

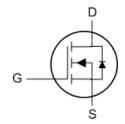
| BVDSS | RDSON | ID | | |
|-------|-------|-----|--|--|
| 60V | 10mΩ | 60A | | |

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- LCD/LED back light

TO-252 Pin Configuration





Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|--------------------------------------|--|------------|------------|
| V_{DS} | Drain-Source Voltage | 60 | V |
| V_{GS} | Gate-Source Voltage | ±20 | V |
| I _D @T _C =25℃ | Continuous Drain Current, V _{GS} @ 10V ¹ | 60 | Α |
| I _D @T _C =100℃ | Continuous Drain Current, V _{GS} @ 10V ¹ | 40 | А |
| I _D @T _A =25℃ | Continuous Drain Current, V _{GS} @ 10V ¹ | 40 | Α |
| I _D @T _A =70°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 30 | А |
| I _{DM} | Pulsed Drain Current ² | 90 | А |
| EAS | Single Pulse Avalanche Energy ³ | 48 | mJ |
| I _{AS} | Avalanche Current | 28 | А |
| P _D @T _C =25℃ | Total Power Dissipation ⁴ | 20 | W |
| P _D @T _A =25℃ | Total Power Dissipation ⁴ | 2.1 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | ℃ |
| T _J | Operating Junction Temperature Range -55 to 150 | | $^{\circ}$ |

Thermal Data

| Symbol | Parameter | Тур. | Max. | Unit |
|------------------|--|------|------|------|
| R _{0JA} | Thermal Resistance Junction-Ambient ¹ | | 62 | °C/W |
| $R_{	heta JC}$ | Thermal Resistance Junction-Case ¹ | | 2 | °C/W |



Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|--------------------------------------|--|---|------|-------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V , I _D =250uA | 60 | | | V |
| $\triangle BV_{DSS}/\triangle T_{J}$ | BV _{DSS} Temperature Coefficient | Reference to 25℃ , I _D =1mA | | 0.057 | | V/°C |
| D | Static Drain-Source On-Resistance ² | V _{GS} =10V , I _D =20A | | 10 | 12 | 0 |
| R _{DS(ON)} | | V _{GS} =4.5V , I _D =10A | | 12 | 15 | mΩ |
| $V_{GS(th)}$ | Gate Threshold Voltage | -V _{GS} =V _{DS} , I _D =250uA | 1.0 | 1.8 | 3.0 | ٧ |
| $\triangle V_{GS(th)}$ | V _{GS(th)} Temperature Coefficient | V _{GS} -V _{DS} , I _D -250uA | | -5.68 | | mV/℃ |
| | Drain Source Leakage Current | V _{DS} =48V , V _{GS} =0V , T _J =25℃ | | | 1 | uA |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =48V , V _{GS} =0V , T _J =55℃ | | | 5 | |
| I _{GSS} | Gate-Source Leakage Current | V_{GS} = $\pm 20 V$, V_{DS} = $0 V$ | | | ±100 | nA |
| gfs | Forward Transconductance | V _{DS} =5V , I _D =15A | | 9 | | S |
| Rg | Gate Resistance | V _{DS} =0V , V _{GS} =0V , f=1MHz | | 1.7 | 3.4 | Ω |
| Q_g | Total Gate Charge (4.5V) | V _{DS} =48V , V _{GS} =4.5V , I _D =15A | | 9 | 36 | |
| Q_gs | Gate-Source Charge | | | 4.5 | 10 | nC |
| Q _{gd} | Gate-Drain Charge | | | 7.5 | 15 | |
| T _{d(on)} | Turn-On Delay Time | V_{DD} =30V , V_{GS} =10V , R_{G} =3.3 Ω , I_{D} =1A ,RL=15 Ω . | | 8.2 | 14.4 | |
| Tr | Rise Time | | | 5.8 | 90 | |
| T _{d(off)} | Turn-Off Delay Time | | | 25 | 73 | ns |
| T _f | Fall Time | | | 8.8 | 15.2 |] |
| C _{iss} | Input Capacitance | V _{DS} =15V , V _{GS} =0V , f=1MHz | | 1896 | 2578 | |
| C _{oss} | Output Capacitance | | | 125 | 203 | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 89 | 136 | |

Guaranteed Avalanche Characteristics

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|--------|--|---|------|------|------|------|
| EAS | Single Pulse Avalanche Energy ⁵ | V _{DD} =25V , L=0.1mH , I _{AS} =28A | 45 | | | mJ |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|-----------------|--|--|------|------|------|------|
| Is | Continuous Source Current ^{1,6} | V _G =V _D =0V , Force Current | | | 40 | Α |
| I _{SM} | Pulsed Source Current ^{2,6} | | | | 90 | Α |
| V_{SD} | Diode Forward Voltage ² | V _{GS} =0V , I _S =1A , T _J =25℃ | | | 1 | V |
| t _{rr} | Reverse Recovery Time | IF=1A ,dl/dt=100A/μs,TJ=25℃ | | 21 | | nS |
| Q _{rr} | Reverse Recovery Charge | | | 16 | | nC |

Note:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.1mH, I_{AS} =28A
- 4.The power dissipation is limited by 150 °C junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

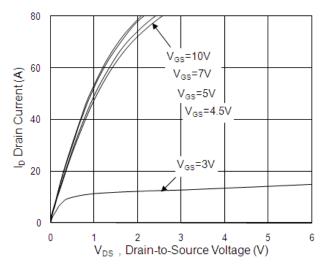


Fig.1 Typical Output Characteristics

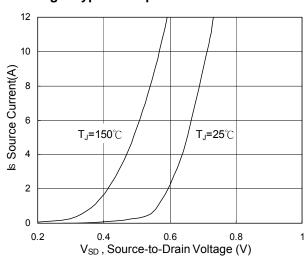


Fig.3 Forward Characteristics of Reverse

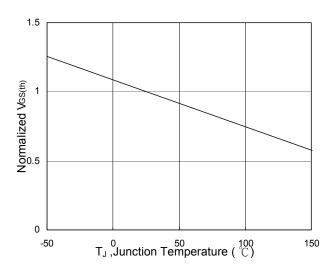


Fig.5 Normalized V_{GS(th)} v.s T_J

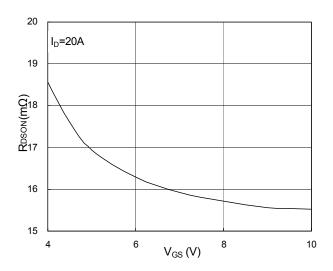


Fig.2 On-Resistance v.s Gate-Source

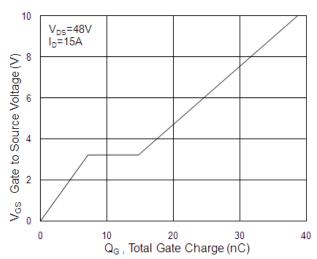


Fig.4 Gate-Charge Characteristics

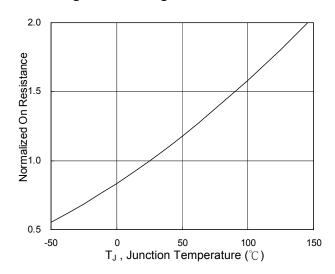
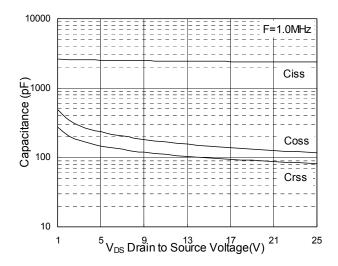


Fig.6 Normalized R_{DSON} v.s T_J







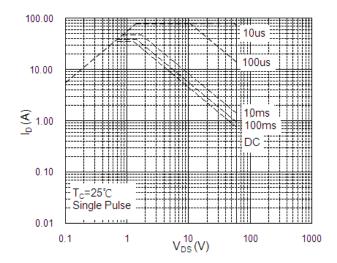


Fig.7 Capacitance

Fig.8 Safe Operating Area

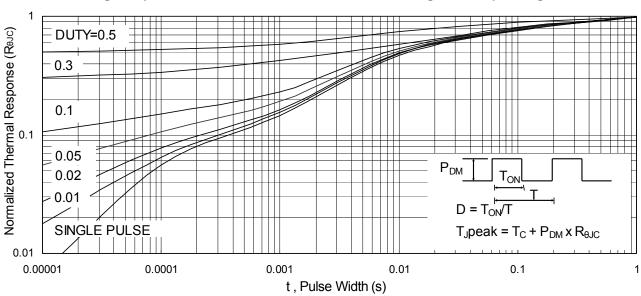


Fig.9 Normalized Maximum Transient Thermal Impedance

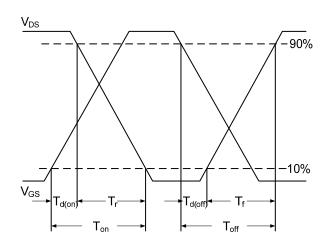


Fig.10 Switching Time Waveform

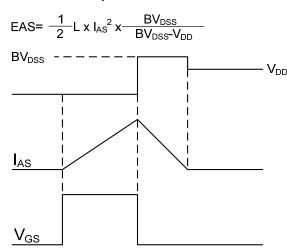


Fig.11 Unclamped Inductive Switching Waveform



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